Session 2 report: Pixel

- Milestones and Schedule
  - ROC
  - Readout scheme
  - EMI and grounding tests
  - Multichip module
  - Plane demo
  - Test stand

Schedule

- FPIX2 readout chip
  - Irradiation tests (SEE): Dec 2000 pre-FPIX2I
  - February 01 pre-FPIX2-TB
  - FPIX2A – expected submission 4th qtr 01
- EMI tests
  - Results May 01
- Test stand
  - PCI available, software ready Feb 01

Schedule (II)

- Readout scheme
  - June 01
- Multichip module
  - A few modules available June/July 01
- Plane demo
  - available for tests early fall 2001

Custom IC

FPIX2 chip

We are working towards a new baseline which won't need another custom IC.

In case another custom IC is needed (serializer, data compression chip), we don't need to prototype it for the baseline review.

BTeV standard test stands

- Pixel is the example of establising a standard test stand
- It’ll be available for testing early next yea

Pixel specific questions

- Working towards a new baseline; goal is to establish a new baseline by next June; depends on EMI effects, LVDS driver on pre-FPIX2_tb, rad-tolerant COTs; this solution doesn't need laser link and serializer
- RF and grounding – work delayed a bit; plan is to test a FPIX1 chip using the beam simulator; expected results by May 2001
- Single Event Effects – SEU, SEGR tests planned for Dec 2000; so far, we haven't done anything special in circuit design; check effects and if necessary implement design changes in FPIX2A